

1A Avg.

30 Volts

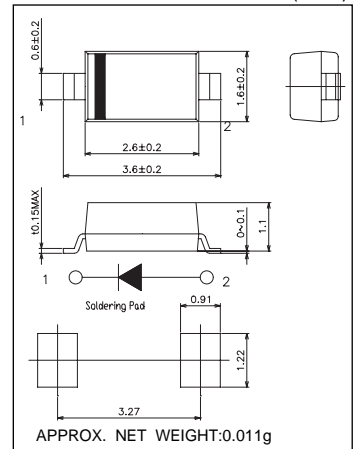
SBD

EP10HY03

最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	30	V
直流順電流 Direct Forward Current	I_{DC}	Tl=120 Tl:Lead Temperature Ta=34 *	1.0 A
平均整流電流 Average Rectified Forward Current	I_o	Tl = 125 VRM=0V Tl:Lead Temperature Ta=35 * VRM=0V	0.7 A
サージ順電流 Surge Forward Current	I_{FSM}	12 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	- 40 ~ + 150	
保存温度範囲 Storage Temperature Range	T_{stg}	- 40 ~ + 150	

OUTLINE DRAWING(mm)



電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j = 25$, $V_{RM} = V_{RRM}$	-	-	0.5	mA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j = 25$, $I_{FM} = 1A$	-	-	0.56	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間* Junction to Ambient*	-	-	270	/W
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	-	-	70	/W

*プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 1 x 1 mm, Both Sides)
(Tl: Lead Temperature)

定格・特性曲線

FIG.1

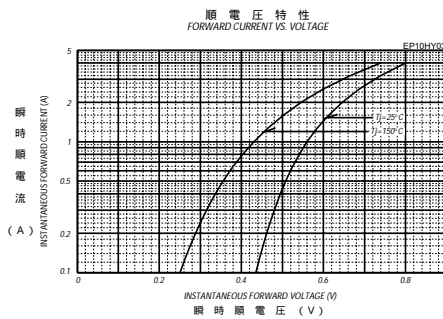


FIG.2

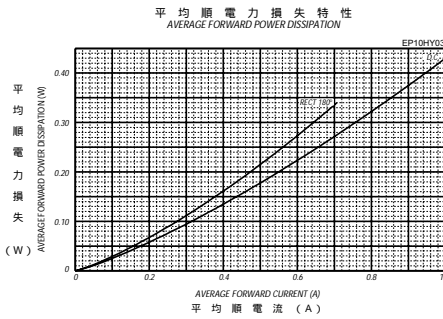


FIG.3

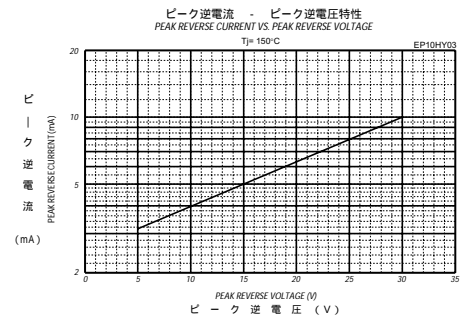


FIG.4

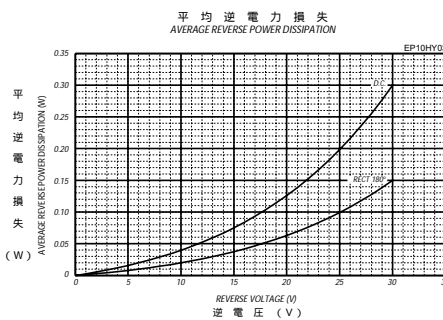


FIG.5

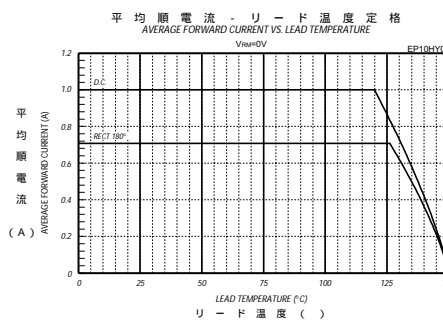


FIG.6

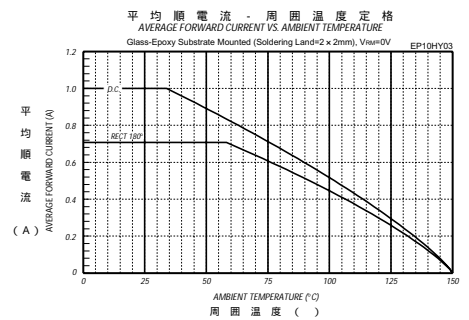


FIG.7

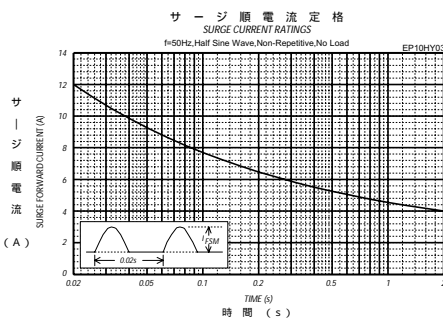


FIG.8

